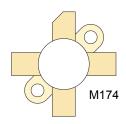


50V, 150W, 175MHz

RF POWER VERTICAL MOSFET

The VRF152 is a gold-metallized silicon n-channel RF power transistor designed for broadband commercial and military applications requiring high power and gain without compromising reliability, ruggedness, or inter-modulation distortion.



FEATURES

- Improved Ruggedness $V_{(BR)DSS} = 130V$
- 150W with 22dB Typical Gain @ 30MHz, 50V
- 150W with 14dB Typical Gain @ 175MHz, 50V
- Excellent Stability & Low IMD
- Common Source Configuration
- · Available in Matched Pairs

- 70:1 Load VSWR Capability at Specified Operating Conditions
- Nitride Passivated
- · Refractory Gold Metallization
- · Low Rds Replacement for MRF151/ BLF177/ SD2941
- RoHS Compliant



Maximum Ratings All Ratings: T_c =25°C unless otherwise specified

Symbol	Parameter	VRF152(MP)	Unit	
V _{DSS}	Drain-Source Voltage	130	V	
I _D	Continuous Drain Current @ T _C = 25°C	20	Α	
V_{GS}	Gate-Source Voltage	±40	V	
P _D	Total Device dissipation @ T _C = 25°C	300	W	
T _{STG}	Storage Temperature Range	-65 to 150	°C	
T_{J}	Operating Junction Temperature	200		

Static Electrical Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage (V _{GS} = 0V, I _D = 50mA)	130			V
R _{DS(ON)}	Drain-Source On-State Resistance ¹ (V _{GS} = 10V, I _D = 10A)		0.13	0.20	Ohms
I _{DSS}	Zero Gate Voltage Drain Current (V _{DS} = 50V, V _{GS} = 0V)			50	μΑ
I _{GSS}	Gate-Source Leakage Current (V _{GS} = ±20V, V _{DS} = 0V)			1.0	μA
g _{fs}	Forward Transconductance (V _{DS} = 10V, I _D = 5A)	5.0	6.2		mhos
V _{GS(TH)}	Gate Threshold Voltage (V _{DS} = 10V, I _D = 100mA)	2.9	3.6	4.4	V

Thermal Characteristics

Symbol	Characteristic		Тур	Max	Unit
$R_{ heta JC}$	R _{BJC} Junction to Case Thermal Resistance			0.60	°C/W

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Dynamic Characteristics

VRF152(MP)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
C _{ISS}	Input Capacitance	V _{GS} = 0V		383		
C _{oss}	Output Capacitance V _{DS} = 50V			215		pF
C _{rss}	Reverse Transfer Capacitance	f = 1MHz		20		

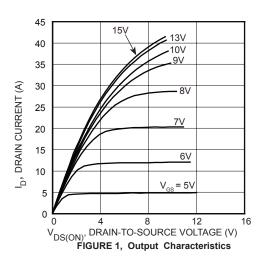
Functional Characteristics

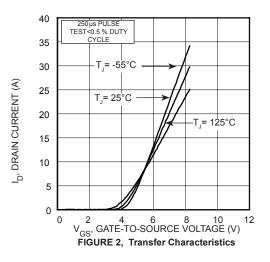
Symbol	Parameter	Min	Тур	Max	Unit
G_{PS}	$f_1 = 30MHz, f_2 = 30.001MHz, V_{DD} = 50V, I_{DQ} = 250mA, P_{out} = 150W_{PEP}^{-1}$	18	22		dB
G_{PS}	f = 175MHz, V _{DD} = 50V, I _{DQ} = 250mA, P _{out} = 150W		14		иь
$\eta_{\scriptscriptstyle D}$	$f_1 = 30MHz, f_2 = 30.001MHz, V_{DD} = 50V, I_{DQ} = 250mA, P_{out} = 150W_{PEP}^{-1}$		50		%
IMD _(d3)	$f_1 = 30MHz, f_2 = 30.001MHz, V_{DD} = 50V, I_{DQ} = 250mA, P_{out} = 150W_{PEP}^{-1}$		-30		dBc
Ψ	$f = 30MHz$, $V_{DD} = 50V$, $I_{DQ} = 250mA$, $P_{out} = 150W$ CW 70:1 VSWR - All Phase Angles, 0.2mSec X 20% Duty Factor	No Degradation in Output Power		Power	

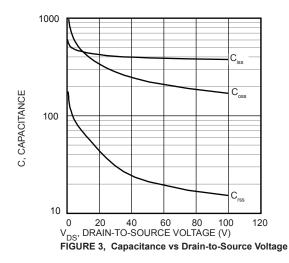
^{1.} To MIL-STD-1311 Version A, test method 2204B, Two Tone, Reference Each Tone

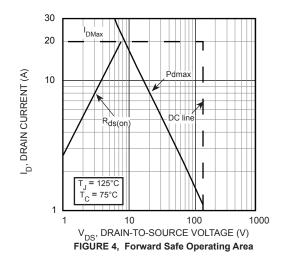
Microsemi reserves the right to change, without notice, the specifications and information contained herein.

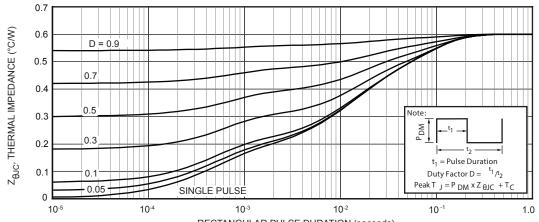
Typical Performance Curves



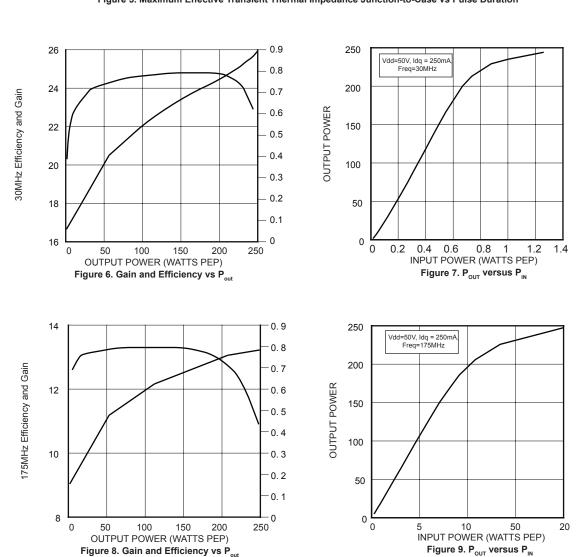




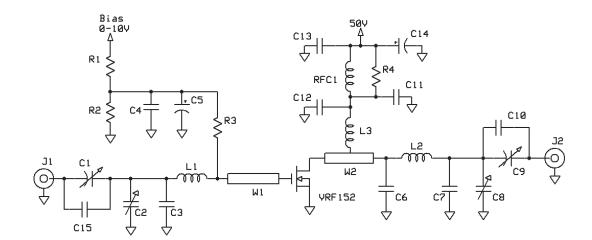




RECTANGULAR PULSE DURATION (seconds)
Figure 5. Maximum Effective Transient Thermal Impedance Junction-to-Case vs Pulse Duration



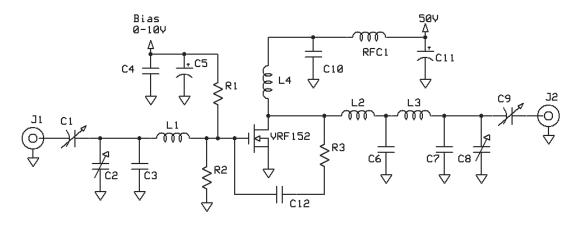
30 MHz test Circuit



C1,2,8,9 - ARCO 463 20-180pF
C3,7 - 120 pF ATC 100B
C4,11-13 - 0.1uF 100V SMT
C5 - 1 uF 15WV tant
C6, C15 - 47pF ATC 100B
C10 - 150pF ATC 100B
C14 - 15uF 100V Elect
W1 W2 - printed line 0.23"x 0.7"

L1 - 4t #20 ga .25"d x .16"L ~120nH L2 - 5t #14 ga .312" dia x .45" ~135nH L3 -7 turns #16 ga 5/16" [D tight. ~250nH R1 R2 - 2.2k ohm 1/4W R3 - 22 ohm 1W SMT R4 - 2.2 ohm 2W RFC1 Fair-Rite 2961666631 (VK200-4B) PCB = FR-4 fiberglass-epoxy er = 4.6

175 MHz test Circuit



C1 C2 C8 - ARCO 463

C3 C7 - 25 pF ATC 100B

C4 C10 C12 - 0.1uF 100Y SMT

C5 - 1 uF 15WY tant

C6 - 250 pF ATC 100B

C9 - ARCO 462

C11 - 15uF 100Y Elect

L1 - 3/4" #18 ga into Hairpin

L2 - printed line 0.2"W \times 0.5" L

L3 - 1" #16 ga into Hairpin

L4 -2 turns #16 ga. 5/16" ID

R1 R2 - 150 ohm 1W

R3 - 470 ohm 3W, Panasonic ECG

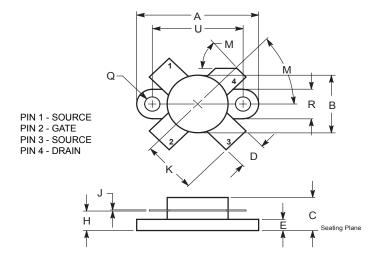
RFC1 Fair-Rite 2961666631 (VK200-4B)

Adding MP at the end of P/N specifies a matched pair where $V_{\text{GS(TH)}}$ is matched between the two parts. V_{TH} values are marked on the devices per the following table.

Code	Vth Range	Code 2	Vth Range
Α	2.900 - 2.975	М	3.650 - 3.725
В	2.975 - 3.050	N	3.725 - 3.800
С	3.050 - 3.125	Р	3.800 - 3.875
D	3.125 - 3.200	R	3.875 - 3.950
E	3.200 - 3.275	S	3.950 - 4.025
F	3.275 - 3.350	Т	4.025 - 4.100
G	3.350 - 3.425	W	4.100 - 4.175
Н	3.425 - 3.500	Х	4.175 - 4.250
J	3.500 - 3.575	Υ	4.250 - 4.325
K	3.575 - 3.650	Z	4.325 - 4.400

 $[{]m V}_{_{
m TH}}$ values are based on Microsemi measurements at datasheet conditions with an accuracy of 1.0%.

.5" SOE Package Outline All Dimensions are ± .005



DIM	INCHES		MILLIMETERS		
I DIIVI	MIN	MAX	MIN	MAX	
Α	0.096	0.990	24.39	25.14	
В	0.465	0.510	11.82	12.95	
С	0.229	0.275	5.82	6.98	
D	0.216	0.235	5.49	5.96	
Е	0.084	0.110	2.14	2.79	
Н	0.144	0.178	3.66	4.52	
J	0.003	0.007	0.08	0.17	
К	0.435		11.0		
М	45° l	MON	45° NOM		
Q	0.115	0.130	2.93	3.30	
R	0.246	0.255	6.25	6.47	
U	0.720	0.730	18.29	18.54	

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